MOSFET, Single N-Channel, POWERTRENCH®

40 V, 10 A, 14 mΩ

General Description

This device has been designed to provide maximum efficiency and thermal performance for synchronous buck converters. The low $r_{DS(on)}$ and gate charge provide excellent switching performance.

Features

- Max $r_{DS(on)} = 14 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 10 \text{ A}$
- Max $r_{DS(on)} = 18 \text{ m}\Omega$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 8.5 \text{ A}$
- Low Profile 0.8 mm maximum in the new package MicroFET 2 x 2 mm
- Free from halogenated compounds and antimony oxides
- RoHS Compliant

Application

• DC-DC Buck Converters

MOSFET MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V _{DS}	Drain to Source Voltage	40	V
V_{GS}	Gate to Source Voltage	±20	٧
I _D	Drain Current - Continuous T _A = 25°C (Note 2a)	10	Α
	Pulsed (Note 4)	80	
P _D	Power dissipation T _A = 25°C (Note 2a)	2.4	W
	Power dissipation T _A = 25°C (Note 2b)	0.9	
T _{J,} T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

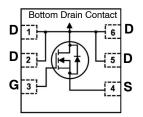
Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 2a)	52	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 2b)	145	



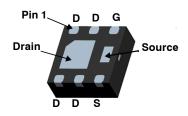
ON Semiconductor®

www.onsemi.com

ELECTRICAL CONNECTION



Single N-Channel MOSFET



MicroFET 2x2 (WDFN6 2x2, 0.65P) CASE 511DB

MARKING DIAGRAM



&Z = Assembly Plant Code &2 = Numeric Date Code

&K = Lot Code

051 = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 16 of this data sheet.

PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Shipping [†]
051	STLJFS014N04M8L	MicroFET 2x2	3000 Units/ Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

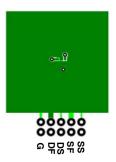
ELECTRICAL CHARACTERISTICS (T_{.1} = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
OFF CHARA	CTERISTICS					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25°C		22		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 32 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
ON CHARAC	CTERISTICS					
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	1.6	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25°C		-5		mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 10 A		11	14	mΩ
		V _{GS} = 4.5 V, I _D = 8.5 A		14	18	
		V _{GS} = 10 V, I _D = 10 A, T _J = 125°C		15	19	
9FS	Forward Transconductance	V _{DD} = 5 V, I _D = 10 A		35		S
DYNAMIC C	HARACTERISTICS					
C _{iss}	Input Capacitance	V _{DS} = 20 V, V _{GS} = 0 V, f = 1MHz		901	1260	
C _{oss}	Output Capacitance	7		251	350	pF
C _{rss}	Reverse Transfer Capacitance	7		16	25	1
R _g	Gate Resistance		0.1	0.6	1.8	Ω
SWITCHING	CHARACTERISTICS					
td _(on)	Turn – On Delay Time	V _{DD} = 20 V, I _D = 10 A,		6.4	13	ns
t _r	Rise Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		1.8	10	1
t _{D(off)}	Turn – Off Delay Time	7		17	31	
t _f	Fall Time	7		1.8	10	
Qg	Total Gate Charge	V _{GS} = 0V to 10 V		14	20	nC
Qg	Total Gate Charge	V _{GS} = 0V to 4.5 V		6.4	9.0	1
Q _{gs}	Total Gate Charge	$V_{DD} = 20 \text{ V},$ $i_D = 10 \text{ A}$		2.4	3.7	1
Q _{gd}	Gate to Source Charge			1.8	2.5	
DRAIN-SOU	RCE DIODE CHARACTERISTICS					
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = 2 A (Note 3)		0.7	1.2	V
		V _{GS} = 0 V, I _S = 10 A (Note 3)		0.8	1.2	1
t _{rr}	Reverse Recovery Time	I _F = 10 A, di/dt = 100 A/μs		23	37	ns
Q _{rr}	Reverse Recovery Charge			6.7	14	nC
	•	•	•	•		•

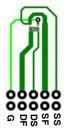
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NOTES:

R_{θ,JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 × 1.5 in. board of FR-4 material. R_{θ,JC} is guaranteed by design while R_{θ,JA} is determined by the user's board design.



 a) 52°C/W when mounted on a 1 in² pad of 2 oz copper.



 b) 145°C/W when mounted on a minimum pad of 2 oz copper.

- 3. Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0%.
- 4. Pulsed I_D limited by junction temperature, td<= 100 μS, please refer to SOA curve for more details.

TYPICAL CHARACTERISTICS T_J = 25°C unless otherwise noted

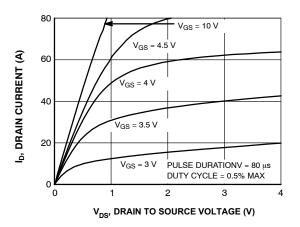


Figure 14. On Region Characteristics

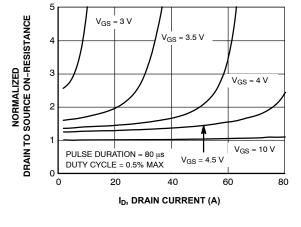


Figure 15. Normalized On-Resistance vs. Drain Current and Gate Voltage

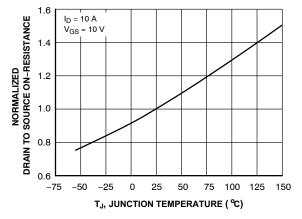


Figure 16. Normalized On Resistance vs. Junction Temperature

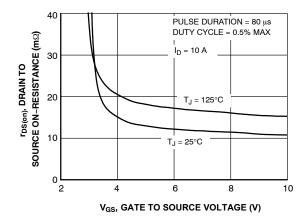


Figure 17. On–Resistance vs. Gate to Source Voltage

TYPICAL CHARACTERISTICS $T_J = 25$ °C unless otherwise noted (continued)

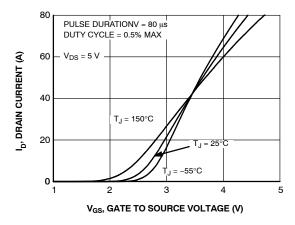


Figure 18. Transfer Characteristics

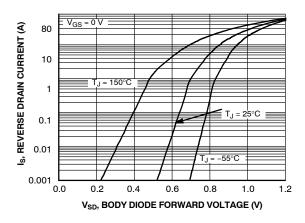


Figure 19. Source to Drain Diode Forward Voltage vs. Source Current

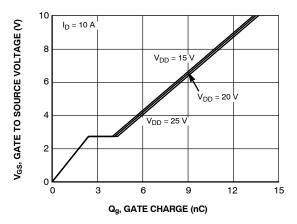


Figure 20. Gate Charge Characteristics

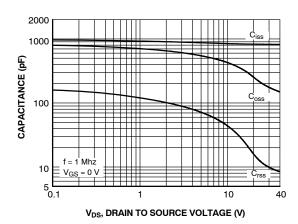


Figure 21. Capacitance vs. Drain to Source Voltage

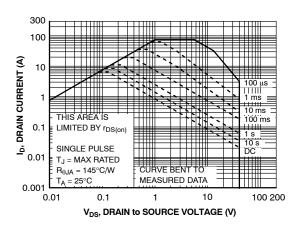


Figure 22. Forward Bias Safe Operating Area

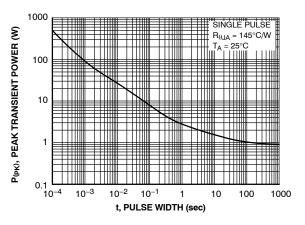


Figure 23. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS $T_J = 25^{\circ}C$ unless otherwise noted (continued)

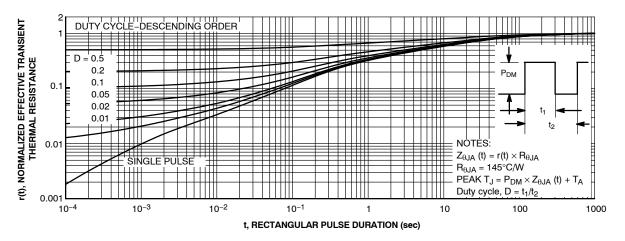
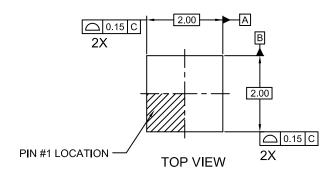


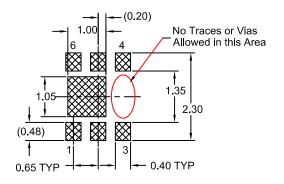
Figure 24. Single Pulse Junction-to-Ambient Transient Thermal Response Curve

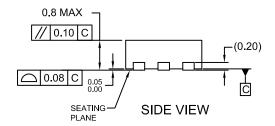
POWERTRENCH is registered trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

WDFN6 2x2, 0.65P CASE 511DB ISSUE O

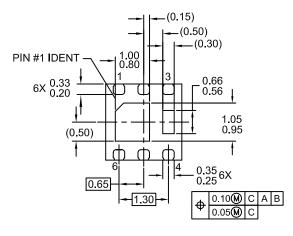
DATE 31 AUG 2016

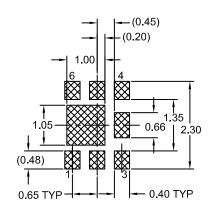












BOTTOM VIEW

RECOMMENDED LAND PATTERN OPT 2

NOTES:

- A. DOES NOT FULLY CONFORM TO JEDEC REGISTRATION MO-229 DATED AUG/2003
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

DOCUMENT NUMBER:	98AON13617G	Electronic versions are uncontrolled ex	•
STATUS:	ON SEMICONDUCTOR STANDARD	accessed directly from the Document Repositions are uncontrolled except when	,
NEW STANDARD:		"CONTROLLED COPY" in red.	
DESCRIPTION:	WDFN6 2X2, 0.65P	PA	GE 1 OF 2

N	Semiconductor®	ON

DOCUMENT	NUMBER:
98AON13617	'G

PAGE 2 OF 2

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION FROM FAIRCHILD MLP06P TO ON SEMICONDUCTOR. REQ. BY B. MARQUIS.	31 AUG 2016

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages.

Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative